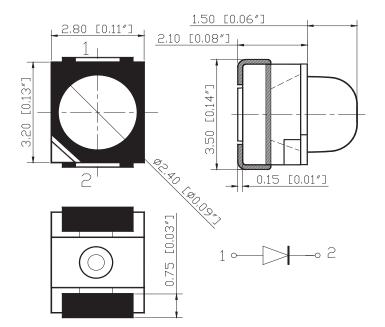
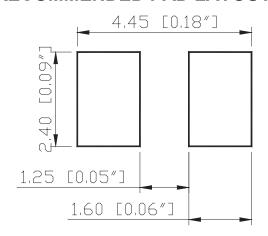


# SPECIFICATION CSD1311R3C-B

### **PACKAGE OUTLINES**



### RECOMMENDED PAD LAYOUT



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm$  0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSD1311R3C-B	InGaAlP	Red	Water Clear	30°	





### **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lr	10	μA	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	125	mA	
Soldering Temperature	Tsol	Max 260°C for 10 sec Max		

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

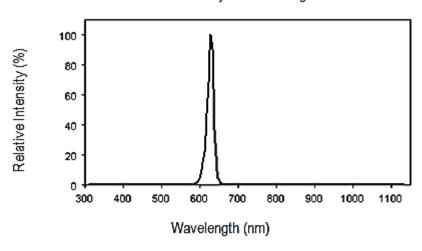
Darameter	Symbol	Toot Condition	Value			Linit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	3200	6000	-	mcd
Forward Voltage	VF	IF = 20mA	-	2.0	2.5	V
Reverse Leakage Current	lR	V <sub>R</sub> = 5V	-	10	-	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	30	-	Deg
Peak Wavelength	<b>λ</b> P	IF = 20mA	1	628	-	nm
Dominant Wavelength	<b>λ</b> D	IF = 20mA	615	620	630	nm

<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.

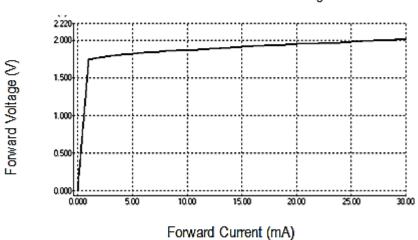


## **OPTICAL CHARACTERISTIC CURVES**

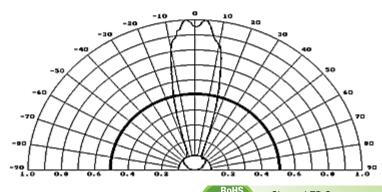
### Relative Intensity vs. Wavelength



### Forward Current vs. Forward Voltage



#### Directive Characteristics

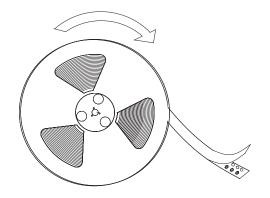




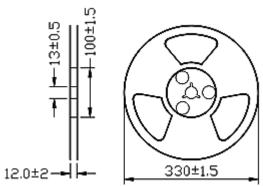
### **PACKAGING SPECIFICATION**

### PACKAGE SPECIFICATIONS

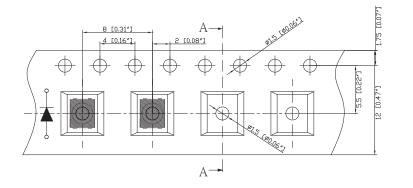
### **Feeding Direction**



Dimensions of Reel (Unit: mm)

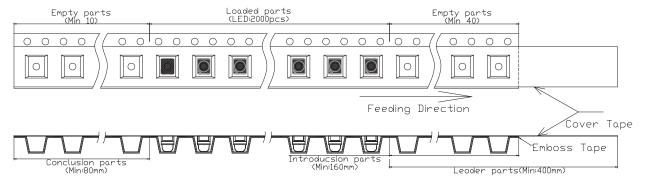


### Dimensions of Tape (Unit: mm)





### Arrangement of Tape



#### Notes:

- 1. Empty component pockets are sealed with top cover tape.
- 2. The maximum number of missing lamp is two.
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 2,000 pcs/Reel

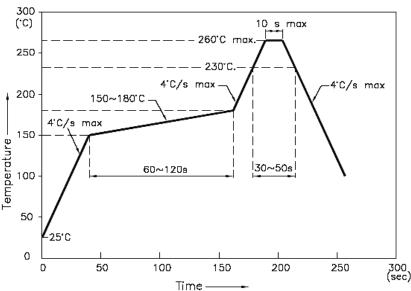




### **SOLDERING CONDITIONS**

#### **REFLOW PROFILE**

Reflow Temp/Time



#### Notes:

- 1. We recommend the reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.
- Soldering Iron

Basic spec is  $\leq$ 5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

- Rework
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil.
- 3. Twin-head type is preferred.

